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#### Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN-EP (7x7)
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#### **Chapter 4 Memory**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0xFFB0 – 0xFFB7	NVBACKKEY				8-Byte Com	parison Key			
0xFFB8 – 0xFFBB	Reserved		_	_	_	_	_	_	_
0xFFBC	Reserved for stor- age of 250 kHz ICGTRM value	_	_	_	_	_	_	_	_
0xFFBD	NVPROT	FPS7	FPS6	FPS5	FPS4	FPS3	FPS2	FPS1	FPDIS
0xFFBE	Reserved for stor- age of 243 kHz ICGTRM value	_	_	_	_	_	_	_	_
0xFFBF	NVOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00

#### Table 4-4. Nonvolatile Register Summary

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the FLASH if needed (normally through the background debug interface) and verifying that FLASH is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC01:SEC00) to the unsecured state (1:0).

### 4.3 RAM

The MC9S08AC16 Series includes static RAM. The locations in RAM below 0x0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait, stop2, or stop3 mode. At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention.

For compatibility with older M68HC05 MCUs, the HCS08 resets the stack pointer to 0x00FF. In the MC9S08AC16 Series, it is usually best to re-initialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale-provided equate file).

LDHX	#RamLast+1	;point one past RAM
TXS		;SP<-(H:X-1)



**Chapter 4 Memory** 

f <sub>Bus</sub>	PRDIV8 (Binary)	DIV5:DIV0 (Decimal)	f <sub>FCLK</sub>	Program/Erase Timing Pulse (5 μs Min, 6.7 μs Max)
20 MHz	1	12	192.3 kHz	5.2 μs
10 MHz	0	49	200 kHz	5 μs
8 MHz	0	39	200 kHz	5 μs
4 MHz	0	19	200 kHz	5 μs
2 MHz	0	9	200 kHz	5 μs
1 MHz	0	4	200 kHz	5 μs
200 kHz	0	0	200 kHz	5 μs
150 kHz	0	0	150 kHz	6.7 μs

Table 4-7. FLASH	Clock Divider Settings
------------------	------------------------

## 4.6.2 FLASH Options Register (FOPT and NVOPT)

During reset, the contents of the nonvolatile location NVOPT are copied from FLASH into FOPT. Bits 5 through 2 are not used and always read 0. This register may be read at any time, but writes have no meaning or effect. To change the value in this register, erase and reprogram the NVOPT location in FLASH memory as usual and then issue a new MCU reset.



#### Figure 4-6. FLASH Options Register (FOPT)

#### Table 4-8. FOPT Register Field Descriptions

Field	Description
7 KEYEN	<ul> <li>Backdoor Key Mechanism Enable — When this bit is 0, the backdoor key mechanism cannot be used to disengage security. The backdoor key mechanism is accessible only from user (secured) firmware. BDM commands cannot be used to write key comparison values that would unlock the backdoor key. For more detailed information about the backdoor key mechanism, refer to Section 4.5, "Security."</li> <li>No backdoor key access allowed.</li> <li>If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset.</li> </ul>
6 FNORED	<ul> <li>Vector Redirection Disable — When this bit is 1, then vector redirection is disabled.</li> <li>0 Vector redirection enabled.</li> <li>1 Vector redirection disabled.</li> </ul>
1:0 SEC0[1:0]	<b>Security State Code</b> — This 2-bit field determines the security state of the MCU as shown in Table 4-9. When the MCU is secure, the contents of RAM and FLASH memory cannot be accessed by instructions from any unsecured source including the background debug interface. For more detailed information about security, refer to Section 4.5, "Security."



Chapter 4 Memory

# 4.6.4 FLASH Protection Register (FPROT and NVPROT)

During reset, the contents of the nonvolatile location NVPROT are copied from FLASH into FPROT. This register can be read at any time. If FPDIS = 0, protection can be increased, i.e., a smaller value of FPS can be written. If FPDIS = 1, writes do not change protection.



<sup>1</sup> Background commands can be used to change the contents of these bits in FPROT.

#### Figure 4-8. FLASH Protection Register (FPROT)

#### Table 4-11. FPROT Register Field Descriptions

Field	Description
7:1 FPS[7:1]	<b>FLASH Protect Select Bits</b> — When FPDIS = 0, this 7-bit field determines the ending address of unprotected FLASH locations at the high address end of the FLASH. Protected FLASH locations cannot be erased or programmed.
0 FPDIS	<ul> <li>FLASH Protection Disable</li> <li>0 FLASH block specified by FPS[7:1] is block protected (program and erase not allowed).</li> <li>1 No FLASH block is protected.</li> </ul>

## 4.6.5 FLASH Status Register (FSTAT)

Bits 3, 1, and 0 always read 0 and writes have no meaning or effect. The remaining five bits are status bits that can be read at any time. Writes to these bits have special meanings that are discussed in the bit descriptions.



Figure 4-9. FLASH Status Register (FSTAT)



#### Chapter 6 Parallel Input/Output



#### Notes:

- 1. Port pins are software configurable with pullup device if input port.
- 2. Pin contains software configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
- 3. IRQ does not have a clamp diode to  $V_{DD}$ . IRQ should not be driven above  $V_{DD}$ .
- 4. Pin contains integrated pullup device.
- 5. PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPEn = 1) and rising edge is selected (KBEDGn = 1).

#### Figure 6-1. Block Diagram Highlighting Parallel Input/Output Pins



Refer to Chapter 8, "Internal Clock Generator (S08ICGV4)" for more information about using port G pins as XTAL and EXTAL pins.

Refer to Chapter 9, "Keyboard Interrupt (S08KBIV1)" for more information about using port G pins as keyboard inputs.

# 6.4 Parallel I/O Control

Reading and writing of parallel I/O is done through the port data registers. The direction, input or output, is controlled through the port data direction registers. The parallel I/O port function for an individual pin is illustrated in the block diagram below.



Figure 6-9. Parallel I/O Block Diagram

The data direction control bits determine whether the pin output driver is enabled, and they control what is read for port data register reads. Each port pin has a data direction register bit. When PTxDDn = 0, the corresponding pin is an input and reads of PTxD return the pin value. When PTxDDn = 1, the corresponding pin is an output and reads of PTxD return the last value written to the port data register. When a peripheral module or system function is in control of a port pin, the data direction register bit still controls what is returned for reads of the port data register, even though the peripheral system has overriding control of the actual pin direction.

When a shared analog function is enabled for a pin, all digital pin functions are disabled. A read of the port data register returns a value of 0 for any bits which have shared analog functions enabled. In general, whenever a pin is shared with both an alternate digital function and an analog function, the analog function



## 7.4.1 Reset Sequence

Reset can be caused by a power-on-reset (POR) event, internal conditions such as the COP (computer operating properly) watchdog, or by assertion of an external active-low reset pin. When a reset event occurs, the CPU immediately stops whatever it is doing (the MCU does not wait for an instruction boundary before responding to a reset event). For a more detailed discussion about how the MCU recognizes resets and determines the source, refer to the Resets, Interrupts, and System Configuration chapter.

The reset event is considered concluded when the sequence to determine whether the reset came from an internal source is done and when the reset pin is no longer asserted. At the conclusion of a reset event, the CPU performs a 6-cycle sequence to fetch the reset vector from 0xFFFE and 0xFFFF and to fill the instruction queue in preparation for execution of the first program instruction.

### 7.4.2 Interrupt Sequence

When an interrupt is requested, the CPU completes the current instruction before responding to the interrupt. At this point, the program counter is pointing at the start of the next instruction, which is where the CPU should return after servicing the interrupt. The CPU responds to an interrupt by performing the same sequence of operations as for a software interrupt (SWI) instruction, except the address used for the vector fetch is determined by the highest priority interrupt that is pending when the interrupt sequence started.

The CPU sequence for an interrupt is:

- 1. Store the contents of PCL, PCH, X, A, and CCR on the stack, in that order.
- 2. Set the I bit in the CCR.
- 3. Fetch the high-order half of the interrupt vector.
- 4. Fetch the low-order half of the interrupt vector.
- 5. Delay for one free bus cycle.
- 6. Fetch three bytes of program information starting at the address indicated by the interrupt vector to fill the instruction queue in preparation for execution of the first instruction in the interrupt service routine.

After the CCR contents are pushed onto the stack, the I bit in the CCR is set to prevent other interrupts while in the interrupt service routine. Although it is possible to clear the I bit with an instruction in the interrupt service routine, this would allow nesting of interrupts (which is not recommended because it leads to programs that are difficult to debug and maintain).

For compatibility with the earlier M68HC05 MCUs, the high-order half of the H:X index register pair (H) is not saved on the stack as part of the interrupt sequence. The user must use a PSHH instruction at the beginning of the service routine to save H and then use a PULH instruction just before the RTI that ends the interrupt service routine. It is not necessary to save H if you are certain that the interrupt service routine does not use any instructions or auto-increment addressing modes that might change the value of H.

The software interrupt (SWI) instruction is like a hardware interrupt except that it is not masked by the global I bit in the CCR and it is associated with an instruction opcode within the program so it is not asynchronous to program execution.



Chapter 7 Central Processor Unit (S08CPUV2)



## 9.3.1 KBI Block Diagram

Figure 9-2 shows the block diagram for a KBI module.



Figure 9-2. KBI Block Diagram

# 9.4 Register Definition

This section provides information about all registers and control bits associated with the KBI module.

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all KBI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.



#### Chapter 10 Timer/PWM (S08TPMV3)

Action	ТРМV3	TPMV2
In Edge-Aligned PWM mode when (CLKSB:CLKSA not = 00), writes to TPMxCnVH:L registers	Update the TPMxCnVH:L registers with the value of their write buffer after both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). <b>Note:</b> If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from \$FFFE to \$FFFF.	Update after both bytes are written and when the TPM counter changes from TPMxMODH:L to \$0000.
In Center-Aligned PWM mode when (CLKSB:CLKSA not = 00), writes to TPMxCnVH:L registers <sup>4</sup>	Update the TPMxCnVH:L registers with the value of their write buffer after both bytes are written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). <b>Note:</b> If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from \$FFFE to \$FFFF.	Update after both bytes are written and when the TPM counter changes from TPMxMODH:L to (TPMxMODH:L - 1).
Center-Aligned PWM	1	I
When TPMxCnVH:L = TPMxMODH:L <sup>5</sup>	Produces 100% duty cycle.	Produces 0% duty cycle.
When TPMxCnVH:L = (TPMxMODH:L - 1) <sup>6</sup>	Produces a near 100% duty cycle.	Produces 0% duty cycle.
TPMxCnVH:L is changed from 0x0000 to a non-zero value <sup>7</sup>	Waits for the start of a new PWM period to begin using the new duty cycle setting.	Changes the channel output at the middle of the current PWM period (when the count reaches 0x0000).
TPMxCnVH:L is changed from a non-zero value to 0x0000 <sup>8</sup>	Finishes the current PWM period using the old duty cycle setting.	Finishes the current PWM period using the new duty cycle setting.
Write to TPMxMODH:L registers in BDM mode		
In BDM mode, a write to TPMxSC register	Clears the write coherency mechanism of TPMxMODH:L registers.	Does not clear the write coherency mechanism.
For more information, refer to Section 10.5.2. "TPM-Counter	Registers (TPMxCNTH:TPMx	CNTL)." [SE110-TPM case 7]

#### Table 10-1. TPMV2 and TPMV3 Porting Considerations (continued)

<sup>2</sup> For more information, refer to Section 10.5.5, "TPM Channel Value Registers (TPMxCnVH:TPMxCnVL)."

<sup>3</sup> For more information, refer to Section 10.6.2.1, "Input Capture Mode."

<sup>4</sup> For more information, refer to Section 10.6.2.4, "Center-Aligned PWM Mode."

<sup>5</sup> For more information, refer to Section 10.6.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 1]

<sup>6</sup> For more information, refer to Section 10.6.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 2]

<sup>7</sup> For more information, refer to Section 10.6.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 3 and 5]



Timer/PWM Module (S08TPMV3)

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
0	00	01	Input capture	Capture on rising edge only
		10		Capture on falling edge only
		11		Capture on rising or falling edge
	01	00	Output compare	Software compare only
		01	Edge-aligned PWM	Toggle output on compare
	1X	10		Clear output on compare
		11		Set output on compare
		10		High-true pulses (clear output on compare)
		X1		Low-true pulses (set output on compare)
1	XX	10	Center-aligned PWM	High-true pulses (clear output on compare-up)
		X1		Low-true pulses (set output on compare-up)

Table 10-8.	Mode,	Edge,	and	Level	Selection
-------------	-------	-------	-----	-------	-----------

## 10.5.5 TPM Channel Value Registers (TPMxCnVH:TPMxCnVL)

These read/write registers contain the captured TPM counter value of the input capture function or the output compare value for the output compare or PWM functions. The channel registers are cleared by reset.



In input capture mode, reading either byte (TPMxCnVH or TPMxCnVL) latches the contents of both bytes into a buffer where they remain latched until the other half is read. This latching mechanism also resets



## 10.7 Reset Overview

### 10.7.1 General

The TPM is reset whenever any MCU reset occurs.

## **10.7.2** Description of Reset Operation

Reset clears the TPMxSC register which disables clocks to the TPM and disables timer overflow interrupts (TOIE=0). CPWMS, MSnB, MSnA, ELSnB, and ELSnA are all cleared which configures all TPM channels for input-capture operation with the associated pins disconnected from I/O pin logic (so all MCU pins related to the TPM revert to general purpose I/O pins).

# 10.8 Interrupts

### 10.8.1 General

The TPM generates an optional interrupt for the main counter overflow and an interrupt for each channel. The meaning of channel interrupts depends on each channel's mode of operation. If the channel is configured for input capture, the interrupt flag is set each time the selected input capture edge is recognized. If the channel is configured for output compare or PWM modes, the interrupt flag is set each time the main timer counter matches the value in the 16-bit channel value register.

All TPM interrupts are listed in Table 10-10 which shows the interrupt name, the name of any local enable that can block the interrupt request from leaving the TPM and getting recognized by the separate interrupt processing logic.

Interrupt	Local Enable	Source	Description
TOF	TOIE	Counter overflow	Set each time the timer counter reaches its terminal count (at transition to next count value which is usually 0x0000)
CHnF	CHnIE	Channel event	An input capture or output compare event took place on channel n

Table 10-10. Interrupt Summary

The TPM module will provide a high-true interrupt signal. Vectors and priorities are determined at chip integration time in the interrupt module so refer to the user's guide for the interrupt module or to the chip's complete documentation for details.

## 10.8.2 Description of Interrupt Operation

For each interrupt source in the TPM, a flag bit is set upon recognition of the interrupt condition such as timer overflow, channel-input capture, or output-compare events. This flag may be read (polled) by software to determine that the action has occurred, or an associated enable bit (TOIE or CHnIE) can be set



#### 10.8.2.2.3 PWM End-of-Duty-Cycle Events

For channels configured for PWM operation there are two possibilities. When the channel is configured for edge-aligned PWM, the channel flag gets set when the timer counter matches the channel value register which marks the end of the active duty cycle period. When the channel is configured for center-aligned PWM, the timer count matches the channel value register twice during each PWM cycle. In this CPWM case, the channel flag is set at the start and at the end of the active duty cycle period which are the times when the timer counter matches the channel value register. The flag is cleared by the two-step sequence described Section 10.8.2, "Description of Interrupt Operation."

## 10.9 The Differences from TPM v2 to TPM v3

1. Write to TPMxCNTH:L registers (Section 10.5.2, "TPM-Counter Registers (TPMxCNTH:TPMxCNTL)) [SE110-TPM case 7]

Any write to TPMxCNTH or TPMxCNTL registers in TPM v3 clears the TPM counter (TPMxCNTH:L) and the prescaler counter. Instead, in the TPM v2 only the TPM counter is cleared in this case.

- 2. Read of TPMxCNTH:L registers (Section 10.5.2, "TPM-Counter Registers (TPMxCNTH:TPMxCNTL))
  - In TPM v3, any read of TPMxCNTH:L registers during BDM mode returns the value of the TPM counter that is frozen. In TPM v2, if only one byte of the TPMxCNTH:L registers was read before the BDM mode became active, then any read of TPMxCNTH:L registers during BDM mode returns the latched value of TPMxCNTH:L from the read buffer instead of the frozen TPM counter value.
  - This read coherency mechanism is cleared in TPM v3 in BDM mode if there is a write to TPMxSC, TPMxCNTH or TPMxCNTL. Instead, in these conditions the TPM v2 does not clear this read coherency mechanism.
- 3. Read of TPMxCnVH:L registers (Section 10.5.5, "TPM Channel Value Registers (TPMxCnVH:TPMxCnVL))
  - In TPM v3, any read of TPMxCnVH:L registers during BDM mode returns the value of the TPMxCnVH:L register. In TPM v2, if only one byte of the TPMxCnVH:L registers was read before the BDM mode became active, then any read of TPMxCnVH:L registers during BDM mode returns the latched value of TPMxCNTH:L from the read buffer instead of the value in the TPMxCnVH:L registers.
  - This read coherency mechanism is cleared in TPM v3 in BDM mode if there is a write to TPMxCnSC. Instead, in this condition the TPM v2 does not clear this read coherency mechanism.
- 4. Write to TPMxCnVH:L registers
  - Input Capture Mode (Section 10.6.2.1, "Input Capture Mode)
    - In this mode the TPM v3 does not allow the writes to TPMxCnVH:L registers. Instead, the TPM v2 allows these writes.
  - Output Compare Mode (Section 10.6.2.2, "Output Compare Mode)
     In this mode and if (CLKSB:CLKSA not = 0:0), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer at the next change of the TPM counter (end of the



TPMxCnVH:L is changed from a non-zero value to 0x0000 [SE110-TPM case 4]
 In this case, the TPM v3 finishes the current PWM period using the old duty cycle setting.
 Instead, the TPM v2 finishes the current PWM period using the new duty cycle setting.

6. Write to TPMxMODH:L registers in BDM mode (Section 10.5.3, "TPM Counter Modulo Registers (TPMxMODH:TPMxMODL))

In the TPM v3 a write to TPMxSC register in BDM mode clears the write coherency mechanism of TPMxMODH:L registers. Instead, in the TPM v2 this coherency mechanism is not cleared when there is a write to TPMxSC register.

 Update of EPWM signal when CLKSB:CLKSA = 00 In the TPM v3 if CLKSB:CLKSA = 00, then the EPWM signal in the channel output is not update

In the TPM v3 if CLKSB:CLKSA = 00, then the EPWM signal in the channel output is not update (it is frozen while CLKSB:CLKSA = 00). Instead, in the TPM v2 the EPWM signal is updated at the next rising edge of bus clock after a write to TPMxCnSC register.

The Figure 10-17 and Figure 10-18 show when the EPWM signals generated by TPM v2 and TPM v3 after the reset (CLKSB:CLKSA = 00) and if there is a write to TPMxCnSC register.

#### EPWM mode TPMxMODH:TPMxMODL = 0x0007 TPMxCnVH:TPMxCnVL = 0x0005

RESET (active low)															
BUS CLOCK				Παπητικ	$\prod$	ΓЦ	IJ	IJ	Ъ	Д	Ц		Ц		
TPMxCNTH:TPMxCNTL			0	,,	1	1	2	3	4	5	6	7	0	1	2
CLKSB:CLKSA BITS			00						   		01	    			
MSnB:MSnA BITS	00			10					   						
ELSnB:ELSnA BITS	00			10					 						
TPMv2 TPMxCHn															
TPMv3 TPMxCHn									i I I						
CHnF BIT (in TPMv2 and TPMv3)															

Figure 10-17. Generation of high-true EPWM signal by TPM v2 and v3 after the reset



# 12.3 Modes of Operation

## 12.3.1 SPI in Stop Modes

The SPI is disabled in all stop modes, regardless of the settings before executing the STOP instruction. During either stop1 or stop2 mode, the SPI module will be fully powered down. Upon wake-up from stop1 or stop2 mode, the SPI module will be in the reset state. During stop3 mode, clocks to the SPI module are halted. No registers are affected. If stop3 is exited with a reset, the SPI will be put into its reset state. If stop3 is exited with an interrupt, the SPI continues from the state it was in when stop3 was entered.

# 12.4 Register Definition

The SPI has five 8-bit registers to select SPI options, control baud rate, report SPI status, and for transmit/receive data.

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all SPI registers. This section refers to registers and control bits only by their names, and a Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

# 12.4.1 SPI Control Register 1 (SPI1C1)

This read/write register includes the SPI enable control, interrupt enables, and configuration options.



Figure 12-5. SPI Control Register 1 (SPI1C1)

Table	12-1.	SPI1C1	Field	Descriptions
-------	-------	--------	-------	--------------

Field	Description
7 SPIE	<ul> <li>SPI Interrupt Enable (for SPRF and MODF) — This is the interrupt enable for SPI receive buffer full (SPRF) and mode fault (MODF) events.</li> <li>Interrupts from SPRF and MODF inhibited (use polling)</li> <li>When SPRF or MODF is 1, request a hardware interrupt</li> </ul>
6 SPE	<ul> <li>SPI System Enable — Disabling the SPI halts any transfer that is in progress, clears data buffers, and initializes internal state machines. SPRF is cleared and SPTEF is set to indicate the SPI transmit data buffer is empty.</li> <li>SPI system inactive</li> <li>SPI system enabled</li> </ul>
5 SPTIE	<ul> <li>SPI Transmit Interrupt Enable — This is the interrupt enable bit for SPI transmit buffer empty (SPTEF).</li> <li>Interrupts from SPTEF inhibited (use polling)</li> <li>When SPTEF is 1, hardware interrupt requested</li> </ul>



Field	Description
4 MSTR	Master/Slave Mode Select         0 SPI module configured as a slave SPI device         1 SPI module configured as a master SPI device
3 CPOL	<ul> <li>Clock Polarity — This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to Section 12.5.1, "SPI Clock Formats" for more details.</li> <li>0 Active-high SPI clock (idles low)</li> <li>1 Active-low SPI clock (idles high)</li> </ul>
2 CPHA	<ul> <li>Clock Phase — This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to Section 12.5.1, "SPI Clock Formats" for more details.</li> <li>0 First edge on SPSCK occurs at the middle of the first cycle of an 8-cycle data transfer</li> <li>1 First edge on SPSCK occurs at the start of the first cycle of an 8-cycle data transfer</li> </ul>
1 SSOE	<b>Slave Select Output Enable</b> — This bit is used in combination with the mode fault enable (MODFEN) bit in SPCR2 and the master/slave (MSTR) control bit to determine the function of the SS pin as shown in Table 12-2.
0 LSBFE	<ul> <li>LSB First (Shifter Direction)</li> <li>0 SPI serial data transfers start with most significant bit</li> <li>1 SPI serial data transfers start with least significant bit</li> </ul>

Table 12-2. SS Pin Function

MODFEN	SSOE	Master Mode	Slave Mode
0	0	General-purpose I/O (not SPI)	Slave select input
0	1	General-purpose I/O (not SPI)	Slave select input
1	0	SS input for mode fault	Slave select input
1	1	Automatic SS output	Slave select input

#### NOTE

Ensure that the SPI should not be disabled (SPE=0) at the same time as a bit change to the CPHA bit. These changes should be performed as separate operations or unexpected behavior may occur.

## 12.4.2 SPI Control Register 2 (SPI1C2)

This read/write register is used to control optional features of the SPI system. Bits 7, 6, 5, and 2 are not implemented and always read 0.







After a repeated start condition (Sr), all other slave devices also compare the first seven bits of the first byte of the slave address with their own addresses and test the eighth  $(R/\overline{W})$  bit. However, none of them are addressed because  $R/\overline{W} = 1$  (for 10-bit devices) or the 11110XX slave address (for 7-bit devices) does not match.



Table 13-10. Master-Receiver Addresses a Slave-Transmitter with a 10-bit Address

After the master-receiver has sent the first byte of the 10-bit address, the slave-transmitter sees an IIC interrupt. Software must ensure the contents of IICD are ignored and not treated as valid data for this interrupt.

## 13.4.3 General Call Address

General calls can be requested in 7-bit address or 10-bit address. If the GCAEN bit is set, the IIC matches the general call address as well as its own slave address. When the IIC responds to a general call, it acts as a slave-receiver and the IAAS bit is set after the address cycle. Software must read the IICD register after the first byte transfer to determine whether the address matches is its own slave address or a general call. If the value is 00, the match is a general call. If the GCAEN bit is clear, the IIC ignores any data supplied from a general call address by not issuing an acknowledgement.

## 13.5 Resets

The IIC is disabled after reset. The IIC cannot cause an MCU reset.

## 13.6 Interrupts

The IIC generates a single interrupt.

An interrupt from the IIC is generated when any of the events in Table 13-11 occur, provided the IICIE bit is set. The interrupt is driven by bit IICIF (of the IIC status register) and masked with bit IICIE (of the IIC control register). The IICIF bit must be cleared by software by writing a 1 to it in the interrupt routine. You can determine the interrupt type by reading the status register.

Interrupt Source	Status	Flag	Local Enable
Complete 1-byte transfer	TCF	IICIF	IICIE
Match of received calling address	IAAS	IICIF	IICIE
Arbitration Lost	ARBL	IICIF	IICIE

Table 13-11. Interrupt Summary

### 13.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the ninth clock to indicate the completion of byte transfer.



result of the conversion is transferred to ADC1RH and ADC1RL upon completion of the conversion algorithm.

If the bus frequency is less than the  $f_{ADCK}$  frequency, precise sample time for continuous conversions cannot be guaranteed when short sample is enabled (ADLSMP=0). If the bus frequency is less than 1/11th of the  $f_{ADCK}$  frequency, precise sample time for continuous conversions cannot be guaranteed when long sample is enabled (ADLSMP=1).

The maximum total conversion time for different conditions is summarized in Table 14-12.

Conversion Type	ADICLK	ADLSMP	Max Total Conversion Time
Single or first continuous 8-bit	0x, 10	0	20 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit	0x, 10	0	23 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	0x, 10	1	40 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit	0x, 10	1	43 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	11	0	5 $\mu$ s + 20 ADCK + 5 bus clock cycles
Single or first continuous 10-bit	11	0	5 $\mu$ s + 23 ADCK + 5 bus clock cycles
Single or first continuous 8-bit	11	1	5 $\mu$ s + 40 ADCK + 5 bus clock cycles
Single or first continuous 10-bit	11	1	5 $\mu$ s + 43 ADCK + 5 bus clock cycles
Subsequent continuous 8-bit; $f_{BUS} \ge f_{ADCK}$	xx	0	17 ADCK cycles
Subsequent continuous 10-bit; $f_{BUS} \ge f_{ADCK}$	xx	0	20 ADCK cycles
Subsequent continuous 8-bit; f <sub>BUS</sub> ≥ f <sub>ADCK</sub> /11	xx	1	37 ADCK cycles
Subsequent continuous 10-bit; $f_{BUS} \ge f_{ADCK}/11$	xx	1	40 ADCK cycles

Table 14-12. Total Conversion Time vs. Control Conditions

The maximum total conversion time is determined by the clock source chosen and the divide ratio selected. The clock source is selectable by the ADICLK bits, and the divide ratio is specified by the ADIV bits. For example, in 10-bit mode, with the bus clock selected as the input clock source, the input clock divide-by-1 ratio selected, and a bus frequency of 8 MHz, then the conversion time for a single conversion is:

Conversion time =  $\frac{23 \text{ ADCK cyc}}{8 \text{ MHz/1}} + \frac{5 \text{ bus cyc}}{8 \text{ MHz}} = 3.5 \text{ }\mu\text{s}$ 

Number of bus cycles =  $3.5 \ \mu s \ x \ 8 \ MHz = 28 \ cycles$ 

#### NOTE

The ADCK frequency must be between  $f_{ADCK}$  minimum and  $f_{ADCK}$  maximum to meet ADC specifications.



## 14.7.2 Sources of Error

Several sources of error exist for A/D conversions. These are discussed in the following sections.

## 14.7.2.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately  $7k\Omega$  and input capacitance of approximately 5.5 pF, sampling to within 1/4LSB (at 10-bit resolution) can be achieved within the minimum sample window (3.5 cycles @ 8 MHz maximum ADCK frequency) provided the resistance of the external analog source ( $R_{AS}$ ) is kept below 5 k $\Omega$ .

Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

### 14.7.2.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance ( $R_{AS}$ ) is high. If this error cannot be tolerated by the application, keep  $R_{AS}$  lower than  $V_{DDAD} / (2^{N*}I_{LEAK})$  for less than 1/4LSB leakage error (N = 8 in 8-bit mode or 10 in 10-bit mode).

### 14.7.2.3 Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a 0.1  $\mu$ F low-ESR capacitor from V<sub>REFH</sub> to V<sub>REFL</sub>.
- There is a 0.1  $\mu$ F low-ESR capacitor from V<sub>DDAD</sub> to V<sub>SSAD</sub>.
- If inductive isolation is used from the primary supply, an additional 1  $\mu$ F capacitor is placed from V<sub>DDAD</sub> to V<sub>SSAD</sub>.
- $V_{SSAD}$  (and  $V_{REFL}$ , if connected) is connected to  $V_{SS}$  at a quiet point in the ground plane.
- Operate the MCU in wait or stop3 mode before initiating (hardware triggered conversions) or immediately after initiating (hardware or software triggered conversions) the ADC conversion.
  - For software triggered conversions, immediately follow the write to the ADC1SC1 with a WAIT instruction or STOP instruction.
  - For stop3 mode operation, select ADACK as the clock source. Operation in stop3 reduces V<sub>DD</sub> noise but increases effective conversion time due to stop recovery.
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive  $V_{DD}$  noise is coupled into the ADC. In these situations, or when the MCU cannot be placed in wait or stop3 or I/O activity cannot be halted, these recommended actions may reduce the effect of noise on the accuracy:

• Place a 0.01  $\mu$ F capacitor (C<sub>AS</sub>) on the selected input channel to V<sub>REFL</sub> or V<sub>SSAD</sub> (this will improve noise issues but will affect sample rate based on the external analog source resistance).



Appendix A Electrical Characteristics and Timing Specifications

# A.5 ESD Protection and Latch-Up Immunity

Although damage from electrostatic discharge (ESD) is much less common on these devices than on early CMOS circuits, normal handling precautions should be used to avoid exposure to static discharge. Qualification tests are performed to ensure that these devices can withstand exposure to reasonable levels of static without suffering any permanent damage.

All ESD testing is in conformity with AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM), the Machine Model (MM) and the Charge Device Model (CDM).

A device is defined as a failure if after exposure to ESD pulses the device no longer meets the device specification. Complete DC parametric and functional testing is performed per the applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Model	Description	Symbol	Value	Unit
	Series Resistance	R1	1500	Ω
Human Body	Storage Capacitance	С	100	pF
	Number of Pulse per pin	Ι	3	
	Series Resistance	R1	0	Ω
Machine	Storage Capacitance	С	200	pF
	Number of Pulse per pin	-	3	
Lateb-up	Minimum input voltage limit		- 2.5	V
Laten-up	Maximum input voltage limit		7.5	V

Table A-4. ESD and Latch-up Test Conditions

 Table A-5. ESD and Latch-Up Protection Characteristics

Num	С	Rating	Symbol	Min	Max	Unit
1	С	Human Body Model (HBM)	V <sub>HBM</sub>	$\pm2000$	_	V
2	С	Machine Model (MM)	V <sub>MM</sub>	$\pm200$	-	V
3	С	Charge Device Model (CDM)	V <sub>CDM</sub>	$\pm500$	-	V
4	С	Latch-up Current at T <sub>A</sub> = 125°C	I <sub>LAT</sub>	± 100	_	mA